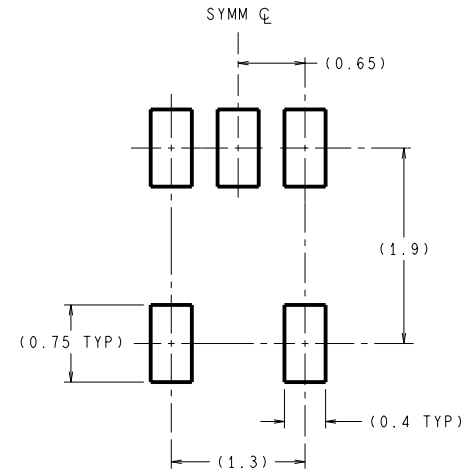
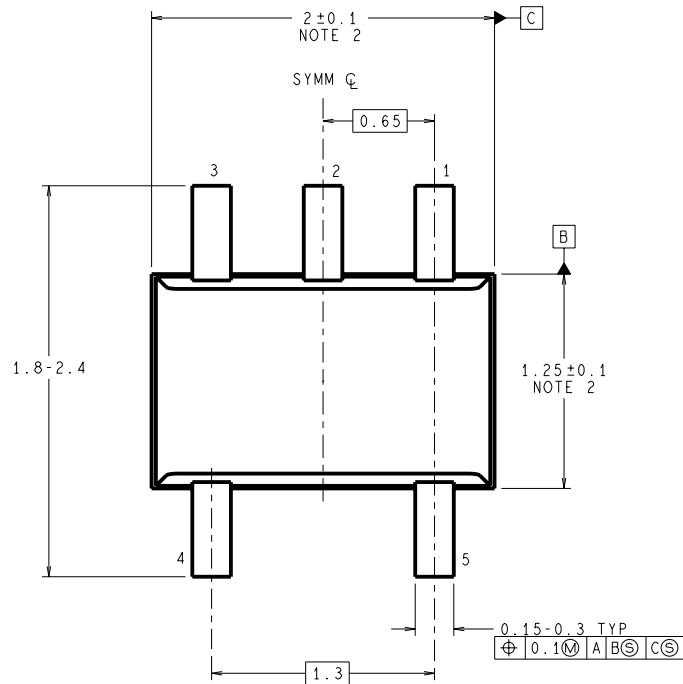
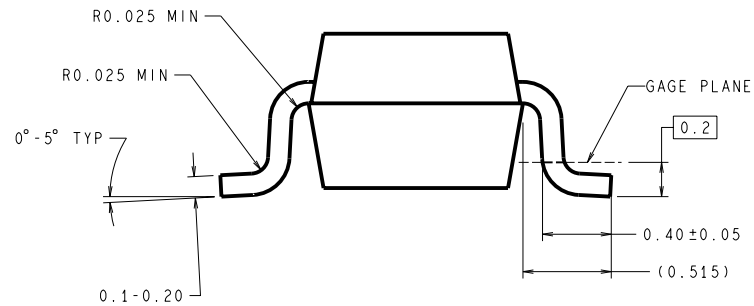
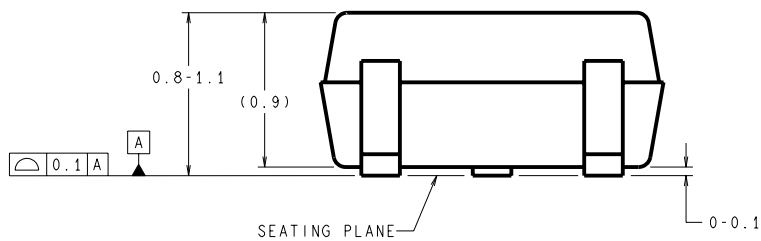


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11819	09/16/1997	KML/MS
B	LEADSPREAD DIM: 1.8-2.4 WAS 2.1±0.1 LAND PATTERN DIST.: 1.9 WAS 1.65	12055	09/11/1998	NOR/MS/AL



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH TO BE 5.08 MICROMETERS MINIMUM LEAD/TIN (SOLDER) ON ALLOY 42.
- DIMENSION DOES NOT INCLUDE MOLD FLASH.

APPROVALS		DATE	National Semiconductor			
DRAWN	K M LOO	09/16/1997	2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DFTG. CHK.			<b>MOLDED PACKAGE, SC70.</b> <b>2x1.25x0.9mm, 3 LEAD.</b> <b>0.65mm PITCH</b>			
ENGR. CHK.	ANTHONY LOW	09/11/1998				
PROJECTION			SCALE	SIZE	DRAWING NUMBER	REV
			N/A	C	(SC)MKT-MAA05A	B
			DO NOT SCALE DRAWING		SHEET 1 of 1	